

Title (en)  
METHOD OF REDUCING ADHESIVE BUILD-UP ON EQUIPMENT SURFACES

Title (de)  
VERFAHREN ZUR REDUZIERUNG DER HAFTUNG AUF GERÄTEOBERFLÄCHEN

Title (fr)  
PROCÉDÉ DE RÉDUCTION DE L'ACCUMULATION D'ADHÉSIF SUR DES SURFACES D'UN ÉQUIPEMENT

Publication  
**EP 4076943 A1 20221026 (EN)**

Application  
**EP 19903824 A 20191219**

Priority  
• US 2019067536 W 20191219  
• CN 201811625604 A 20181228

Abstract (en)  
[origin: WO2020139703A1] Build-up of adhesive on process equipment is reduced or even eliminated by increasing the running temperature of process equipment used to guide substrates as they are conveyed along a system used to apply adhesive and form laminates. Preferably, the process equipment is heated to a temperature of at least about 5°C, preferably at least about 10°C, and most preferably at least about 15°C, above the crossover temperature of the adhesive, and at most about 60°C, preferably at most about 50°C, and most preferably at most about 45°C, above the crossover temperature. This method is particularly beneficial when using hot melt adhesives to form laminates with permeable substrates, such as low basis weight nonwovens, for use in disposable absorbent articles. A system for applying a hot melt adhesive to a substrate comprises a heater for providing heat to the process equipment and, optionally, a chiller for cooling the process equipment.

IPC 8 full level  
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CPC (source: CN EP US)  
**B32B 3/266** (2013.01 - EP); **B32B 5/022** (2013.01 - EP US); **B32B 5/26** (2013.01 - EP); **B32B 7/12** (2013.01 - EP); **B32B 15/14** (2013.01 - US); **B32B 25/10** (2013.01 - EP); **B32B 27/12** (2013.01 - EP); **B32B 27/32** (2013.01 - EP); **B32B 37/06** (2013.01 - CN EP); **B32B 37/12** (2013.01 - EP); **B32B 37/1207** (2013.01 - CN US); **B32B 38/0012** (2013.01 - US); **B32B 41/00** (2013.01 - US); **B32B 37/0053** (2013.01 - EP); **B32B 37/08** (2013.01 - EP); **B32B 2037/1215** (2013.01 - EP US); **B32B 2037/243** (2013.01 - EP); **B32B 2255/02** (2013.01 - EP); **B32B 2255/26** (2013.01 - EP); **B32B 2307/718** (2013.01 - EP); **B32B 2555/02** (2013.01 - EP US)

Citation (search report)  
See references of WO 2020139703A1

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KH MA MD TN

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